



Product Change Notification - JAON-19XMLP616

Date:

22 May 2019

Product Category:

Memory

Affected CPNs:**Notification subject:**

CCB 3815 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K wafer technology available in 8L DFN (2x3x0.9mm) package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K wafer technology available in 8L DFN (2x3x0.9mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 30, 2019 (date code: 1927)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts



Time Table Summary:

	May 2019					June 2019				
Workweek	18	19	20	21	22	23	24	25	26	27
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date										X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

May 22, 2019: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on June 30, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN JAON-19XMLP616_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

24AA01T-I/MC
24AA02T-I/MC
24AA04T-E/MC
24AA08T-I/MC
24AA16-I/MC
24AA16T-I/MC
24AA32AT-I/MC
24AA32AT-I/MCB27
24AA64T-I/MC
24LC01BT-E/MC
24LC01BT-I/MC
24LC02BT-I/MC
24LC04BT-I/MC
24LC08BT-I/MC
24LC16B-E/MC
24LC16B-I/MC
24LC16BT-E/MC
24LC16BT-I/MC
24LC32AT-E/MC
24LC32AT-I/MC
24LC64T-I/MC
93AA46AT-I/MC
93AA46BT-I/MC
93AA46CT-I/MC
93AA56AT-I/MC
93AA56BT-I/MC
93AA56CT-I/MC
93AA66AT-I/MC
93AA66BT-I/MC
93AA66CT-I/MC
93AA76CT-I/MC
93AA86CT-I/MC
93C46AT-I/MC
93C46BT-I/MC
93C46CT-I/MC
93C56AT-I/MC
93C56BT-I/MC
93C56CT-I/MC
93C66AT-I/MC
93C66BT-I/MC
93C66CT-I/MC
93C76CT-I/MC
93C86CT-I/MC
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